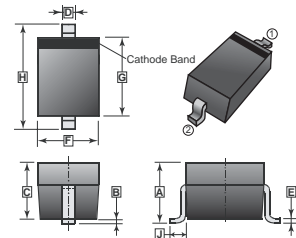


RoHS Compliant Product
 A suffix of "-C" specifies halogen & lead-free

SOD-323

FEATURES

- High Current Capability
- Extremely Low Thermal Resistance
- For Surface Mount Application
- Higher Temp Soldering : 250°C for 10 Seconds at Terminals
- Low Forward Voltage



MECHANICAL DATA

- Case: Molded Plastic
- Epoxy: UL 94V-0 Rate Flame Retardant
- Lead: Solderable per MIL-STD-202, method 208 guaranteed
- Polarity: Color Band Denotes Cathode End
- Mounting Position: Any

REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	1.05	REF.	E	0.080	0.180
B	0.20	REF.	F	1.15	1.45
C	0.80	1.00	G	1.60	1.80
D	0.25	0.40	H	2.30	2.70

MARKING CODE

SF

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T_A=25°C unless otherwise specified)

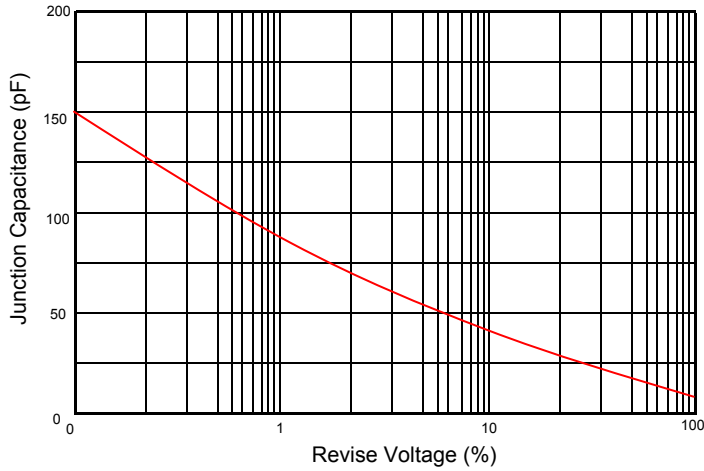
PARAMETER	SYMBOL	RATING	UNITS
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	40	V
Working Peak Reverse Voltage	V _{RWM}	40	V
Maximum DC Blocking Voltage	V _R	40	V
Average Forward Current @ T _J =25°C	I _{F(AV)}	0.5	A
Peak Forward Current @ 8.3 ms Half Sine	I _{FSM}	10	A
Maximum Instantaneous Forward Voltage I _{FM} = 0.5 A, T _A = 25°C	V _{F1}	0.5	V
Maximum Instantaneous Forward Voltage I _{FM} = 0.5 A, T _A = 125°C	V _{F2}	0.38	V
Maximum DC Reverse Current At Rated DC Blocking Voltage @ T _J = 25°C	I _{R1}	0.1	mA
Maximum DC Reverse Current At Rated DC Blocking Voltage @ T _J = 125°C	I _{R2}	5	mA
Typical Junction Capacitance (Note 1)	C _J	160	pF
Typical Thermal Resistance (Note 2)	R _{θJA}	488	°C/W
Operating Temperature Range	T _J	150	°C
Storage temperature	T _{STG}	150	°C

Notes:

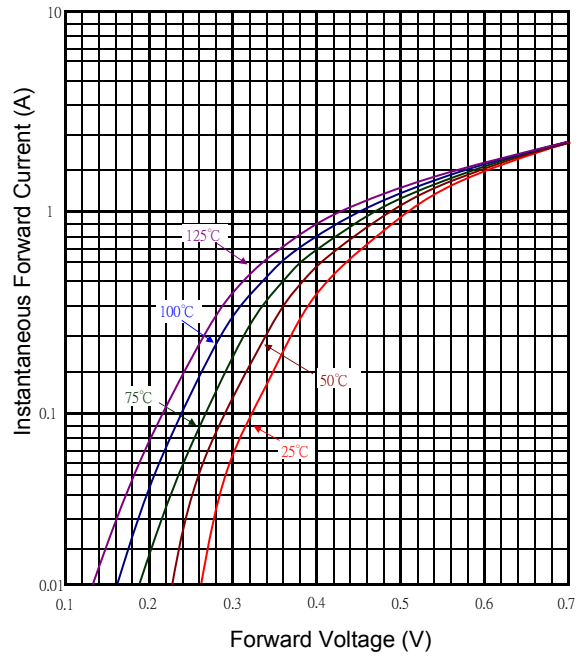
1. Measured at 1MHZ and applied reverse of 0V DC.
2. FR-4 PCB, 2 oz. 0.65mm × 1.35mm copper pad.

RATINGS AND CHARACTERISTIC CURVES

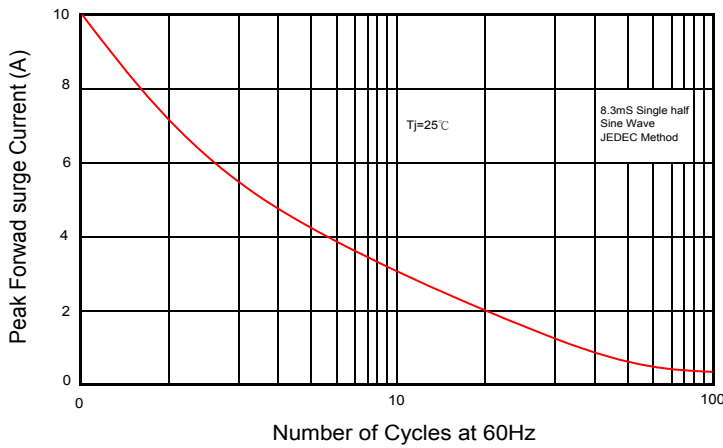
Typical Junction Capacitance



Typical Forward Characteristic



Maximum Non- Repetitive Forward Surge Current



Typical Reverse Characteristic

